IEEE 802.3 NEA Ad hoc Meeting 12 Nov 2024 Hybrid Plenary Session
Location: Vancouver, British Columbia Canada

Unapproved Meeting Minutes, prepared by Jon Lewis
Session called to order at 8:30 pm PST (all times PST), 12 Nov 2024
Meeting called to order by Jon Lewis, IEEE 802.3 NEA Chair

Chair gave meeting introduction.
Chair identified John D'Ambrosia as recording secretary for meeting.

Presentation #1	**Agenda**
Presenter	Jon Lewis
URL	https://www.ieee802.org/3/ad_hoc/ngrates/public/24_11/agenda_nea_241112.pdf

Agenda – chair asked if there were any comments on the agenda. There were none. Chair asked if there were any objections to the agenda, there were none, and the agenda was considered approved.

Approval of minutes:
https://www.ieee802.org/3/ad_hoc/ngrates/public/calls/24_1002/minutes_nea_241002_unapproved.pdf
https://www.ieee802.org/3/ad_hoc/ngrates/public/calls/24_1007/index.html

Chair asked if there were any modifications of the minutes needed. No one responded.
Chair asked if there were any objections to the approval of the minutes. There were none, and the chair ruled the minutes were approved.

Mr. Lewis reviewed IEEE SA Pre-PAR Patent Policy. See Slide #6.

Mr. Lewis noted from Slide #9 and noted by participating in this activity, you agree to comply with the IEEE Code of Ethics, all applicable laws, and all IEEE policies and procedures including but not limited to the IEEE SA Copyright Policy.

Mr. Lewis noted from Slide #12 Participants in the IEEE SA "individual process" shall act independently of others, including employers. By participating in standards activities using the "individual process", you are deemed to accept these requirements then you shall immediately cease any participation.

Chair reviewed NEA information and meeting decorum. See Slides #15-21.

Mr. Lewis turned over the Chair to Mr. D'Ambrosia.

Presentation #2	**Future SMF Needs**
Presenters	Earl Parsons
URL	https://www.ieee802.org/3/ad_hoc/ngrates/public/24_11/parsons_nea_01_2411.pdf

Discussion
There were questions of clarification and discussion on the presentation.

Presentation #3	**Call for a "State of the ODN" Project**
Presenters	Frank Effenberger
URL	https://www.ieee802.org/3/ad_hoc/ngrates/public/24_11/24_11_Adhoc_Effenberger_1.pdf

Discussion
There were questions of clarification and discussion on the presentation. The Chair noted that any survey or questionnaire would need to be approved by IEEE legal. It was noted that the presentation was in scope for the NEA as it covered PON networking, and the output of the activity would be the meeting records. The chair noted that no

“security” is provided for submitted raw data, and noted in past individuals would provide summaries of data without submitting the actual data. It was also noted that while the presentation noted possibly needed funding, this was in conflict with the ICAID for the NEA, which stated no funding was necessary.

Chair noted that the meeting time had expired and adjourned the meeting.

Meeting adjourned at 9:39pm.

IMAT Attendance

Name	**Employer**	**Affiliation**
Beauregard, Francois	Belden Canada ULC	Belden
Bruckman, Leon	Huawei Technologies Co., Ltd	Nvidia
Castro, Jose	Panduit	Panduit Corp.
Choudhury, Golam	OFS	OFS
Cole, Christopher R	Finisar Corporation	Coherent Corp.
D'Ambrosia, John	Futurewei Technologies, U.S. Subsidiary of Huawei	Futurewei Technologies, U.S. Affiliate of Huawei
Donahue, Curtis	Rohde & Schwarz	Rohde & Schwarz
Effenberger, Frank	Futurewei Technologies	Futurewei Technologies
Ferretti, Vincent	Corning Incorporated	Corning Incorporated
Ghiasi, Ali	Ghiasi Quantum LLC	Ghiasi Quantum LLC; Marvell Semiconductor, Inc.
Goto, Hideki	Toyota Motor Corporation	Toyota Motor Corporation
Huang, Kechao		Huawei Technologies Co., Ltd
HYAKUTAKE, YASUHIRO	Orbray Co., Ltd.	Orbray Co., Ltd.
Isono, Hideki	Fujitsu Optical Components Limited	Fujitsu Optical Components Limited
Johnson, John	Broadcom Corporation	Broadcom Corporation
Jones, Peter	Cisco Systems, Inc.	Cisco Systems, Inc.
Kawatsu, Yasuaki	APRESIA Systems	APRESIA Systems
Kikuta, Tomohiro	Orbray Co., Ltd.	Orbray Co., Ltd.
Kondo, Taiji	Dexerials Corporation	Dexerials Corporation
Lee, Sylvanus	Leviton Manufacturing Co.	Leviton Manufacturing Co.
Lewis, Jon	Dell Technologies	Dell Technologies
LI, ERGE	Huawei Technologies Co., Ltd	Huawei
Li, Pei-Rong	MediaTek Inc.	MediaTek Inc.
Little, Terrance	Foxconn Electronics Inc.	Foxconn Electronics Inc.
Luo, Yuanqiu	Futurewei Technologies	Futurewei Technologies
Malicoat, David	Malicoat Networking Solutions	Malicoat Networking Solutions; SENKO Advanced Components
Maniloff, Eric	Ciena Corporation	Ciena Corporation
Marques, Flavio	FURUKAWA ELECTRIC	FURUKAWA ELECTRIC
mi, guangcan	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Muller, Shimon	Enfabrica Corp.	Enfabrica
MURAKAMI, YUKI	FUJITSU	FUJITSU
NIIHARA, YOSHIHIRO	Fujikura Ltd.	Fujikura Ltd.
OGAWA, SHOJI	Fujitsu Optical Components Limited	Fujitsu Optical Components Limited
Parkholm, Ulf	Telefon AB LM Ericsson	Telefon AB LM Ericsson
Parsons, Earl	CommScope, Inc.	CommScope, Inc.
Peeters Weem, Jan	Maxim Integrated Products	CONSULTANT
Rodes, Roberto	II-VI	II-VI
Shah, Anup	Siemens Corporation	Siemens EDA
Shiino, Masato	FURUKAWA ELECTRIC	FURUKAWA ELECTRIC
Srivastava, Atul	NEL-America	NTT Electronics

Name	**Employer**	**Affiliation**
TAKAHARA, TOMOO	FUJITSU LABORATORIES LIMITED	FUJITSU LIMITED
TAN, SISI	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Thompson, Geoffrey	GraCaSI S.A.	INDEPENDENT
Ulrichs, Ed	Intel	Intel
Wienckowski, Natalie	IVN Solutions LLC	IVN Solutions LLC; Ethernovia
Yamazaki, Kinya	APRESIA Systems	APRESIA Systems
Yin, Shuang		Google
Zhang, Tingting	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Zhuang, Yan	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Zivny, Pavel	IEEE member / Self Employed	IEEE member / Self Employed